ASSOCIATION CONNECTING ELECTRONICS INDUSTRIESS International and Pa	IPC. Bannockl	ourn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	bstances v all lower	within the manufactule level materials for w	urer listed which the	item. Note: manufacture	if the item is an as er has engineering	sembly with low responsibility.	
	-21.1 IPC Web Site for Information on IPC-1752 Standard For http://www.ipc.org/IPC-175x Dis				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	als and Mfg Information				
Supplier Information														
Company name* Con			Company unique ID			Unique ID Authority					Response Date*			
onsemi											2025-06-04			
ontact Name Title - Contact			ct	I			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product En			ict Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repre			esentative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Pro-			Product Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	tive Date Version Manufacturing Sit		Ianufacturing Site		Weight*	UOM	Unit Type	
	SBRS81	RS8130LT3G REC SMB SPECIA		TAL SHTKY		2025-06-04		V	VN5		101.45	mg	Each	
Ianufacturing Proccess Informa	ation		·			•								
Terminal Plating / Grid Array M	Iaterial 7	erial Terminal Base Allo		J-STD-020 MSL Rating		Peak Proce	Peak Process Body Temperat		ure Max Time at Peak Temp		ature Num	ber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Al		CU Alloy	1			<b>260</b> C		С	30 seco		seconds 3			
omments														
vel 1 - maximum time at peak temperat	ture during so	ldering is 10-3	0 seconds											
or more information regarding materia	l composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Dibutyl phthalate (DIBP).										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for uses that arise regarding information the Supplier provides in thi												
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.12	mg	Supplier	Silicon (Si)	7440-21-3		1.12	mg
Die Attach Solder	3.45	mg	Supplier	Silver (Ag)	7440-22-4		0.0862	mg
			А	Lead (Pb)	7439-92-1	7a	3.1913	mg
			Supplier	Tin (Sn)	7440-31-5		0.1725	mg
Lead Frame	46.99	mg	Supplier	Zinc (Zn)	7440-66-6		0.047	mg
			Supplier	Iron (Fe)	7439-89-6		1.1278	mg
			Supplier	Copper (Cu)	7440-50-8		45.8153	mg
Mold Compound-Black	48.07	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		4.807	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2403	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		6.9701	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		31.2455	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		4.807	mg
Plating	1.82	mg	Supplier	Tin (Sn)	7440-31-5		1.82	mg